

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.06415	100.0	1.29
Subtotal				0.06415	100	1.29
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.0746	100.0	1.5
Subtotal				0.0746	100	1.5
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.00096	2.0	0.0194
	Lead alloy	Silver (Ag)	7440-22-4	0.00121	2.5	0.02425
	Lead alloy	Lead (Pb)	7439-92-1	0.04607	95.5	0.92635
	Subtotal			0.04824	100	0.97
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.74599	100.0	15
Subtotal				0.74599	100	15
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02114	0.03	0.4251
	Copper alloy	Iron (Fe)	7439-89-6	0.07047	0.1	1.417
	Copper alloy	Copper (Cu)	7440-50-8	70.23831	99.67	1,412.3239
	Copper alloy	Silver (Ag)	7440-22-4	0.14094	0.2	2.834
	Subtotal			70.47086	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.85875	6.5	37.375
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.57538	16.0	92
	Filler	Silica fused	60676-86-0	20.30327	71.0	408.25
	Flame retardant	Metal hydroxide		1.85875	6.5	37.375
	Subtotal			28.59615	100	575
	Total			99.99999	100	NaN

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